

CLAIMS

1. A printed wiring board unit, wherein:
a first component is mounted on a printed
5 wiring board;

an auxiliary substrate for hierarchical
mounting is mounted next to the mounted first
component on the printed wiring board;

a second component larger in size than the
10 first component is mounted above the first component,
the second component being supported on the
auxiliary substrate for hierarchical mounting with
terminals of the second component being connected
thereto; and

15 the auxiliary substrate for hierarchical
mounting has component pads on an upper surface
thereof and printed wiring board pads on a lower
surface thereof, the component pads being connected
to the terminals of the second component, the
20 printed wiring board pads being connected to pads on
the printed wiring board, the component pads and the
printed wiring board pads being electrically
connected, the printed wiring board pads being more
dispersed than the component pads.

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2. A printed wiring board unit, wherein:
a first component is mounted on a printed
wiring board;

an auxiliary substrate for hierarchical
30 mounting is mounted next to the mounted first
component on the printed wiring board;

a second component larger in size than the
first component is mounted above the first component,
the second component being supported on the
35 auxiliary substrate for hierarchical mounting with
terminals of the second component being connected
thereto;

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the second component has a plurality of ground terminals; and

the auxiliary substrate for hierarchical mounting has a ground layer inside thereof,
5 component pads on an upper surface thereof, and printed wiring board pads on a lower surface thereof, the component pads being connected to the terminals of the second component, the printed wiring board pads being connected to pads on the printed wiring
10 board, the component pads and the printed wiring board pads being electrically connected, the component pads including component ground pads connected to the ground terminals of the second component and to the ground layer connected to a
15 ground pad for the printed wiring board, the printed wiring board pads being more dispersed than the component pads.

3. A printed wiring board unit, wherein:
20 a first component is mounted on a printed wiring board;

an auxiliary substrate for hierarchical mounting is mounted next to the mounted first component on the printed wiring board;

25 a second component larger in size than the first component is mounted above the first component, the second component being supported on the auxiliary substrate for hierarchical mounting with terminals of the second component being connected
30 thereto;

the second component has a plurality of power supply terminals of equal potentials; and

the auxiliary substrate for hierarchical mounting has a power supply layer inside thereof,
35 component pads on an upper surface thereof, and printed wiring board pads on a lower surface thereof, the component pads being connected to the terminals

of the second component, the printed wiring board pads being connected to pads on the printed wiring board, the component pads and the printed wiring board pads being electrically connected, the
5 component pads including component power supply pads connected to the power supply terminals of the second component and to the power supply layer connected to a power supply pad for the printed wiring board, the printed wiring board pads being
10 more dispersed than the component pads.

4. A printed wiring board unit, wherein:
a first component is mounted on a printed wiring board;

15 an auxiliary substrate for hierarchical mounting is mounted next to the mounted first component on the printed wiring board;

a second component larger in size than the first component is mounted above the first component,
20 the second component being supported on the auxiliary substrate for hierarchical mounting with terminals of the second component being connected thereto;

the second component has a plurality of
25 ground terminals and a plurality of power supply terminals of equal potentials; and

the auxiliary substrate for hierarchical mounting has a ground layer and a power supply layer inside thereof, component pads on an upper surface
30 thereof, and printed wiring board pads on a lower surface thereof, the component pads being connected to the terminals of the second component, the printed wiring board pads being connected to pads on the printed wiring board, the component pads and the
35 printed wiring board pads being electrically connected, the component pads including component ground pads connected to the ground terminals of the

second component and to the ground layer connected to a ground pad for the printed wiring board, the component pads including component power supply pads connected to the power supply terminals of the
5 second component and to the power supply layer connected to a power supply pad for the printed wiring board, the printed wiring board pads being more dispersed than the component pads.

10 5. The printed wiring board unit as claimed in claim 1, wherein a chip component is mounted on the upper surface of the auxiliary substrate for hierarchical mounting.

15 6. A printed wiring board unit, wherein:
a first component is mounted on a printed wiring board;

a first auxiliary substrate for hierarchical mounting is mounted next to the mounted
20 first component on the printed wiring board;

an auxiliary printed wiring board is connected to and supported on the first auxiliary substrate for hierarchical mounting at a position above the first component;

25 a second component is mounted on the auxiliary printed wiring board;

a second auxiliary substrate for hierarchical mounting is mounted next to the mounted second component on the auxiliary printed wiring
30 board;

a third component larger in size than the second component is mounted above the second component, the third component being supported on the second auxiliary substrate for hierarchical
35 mounting with terminals of the third component being connected thereto;

the second auxiliary substrate for

hierarchical mounting has component pads on an upper surface thereof, the component pads being connected to terminals of the second component;

the first auxiliary substrate for
5 hierarchical mounting has printed wiring board pads on a lower surface thereof, the printed wiring board pads being connected to pads on the printed wiring board;

the component pads and the printed wiring
10 board pads are electrically connected; and

the printed wiring board pads are more dispersed than the component pads.

7. An auxiliary substrate for
15 hierarchical mounting mounted next to a first component mounted on a printed board, the auxiliary substrate for hierarchical mounting comprising:

component pads on an upper surface thereof
and printed wiring board pads on a lower surface
20 thereof, the component pads being connected to terminals of a second component larger in size than the first component, the printed wiring board pads being connected to pads on the printed wiring board, the component pads and the printed wiring board pads
25 being electrically connected, the printed wiring board pads being more dispersed than the component pads.

8. An auxiliary substrate for
30 hierarchical mounting mounted next to a first component mounted on a printed board, the auxiliary substrate for hierarchical mounting comprising:

a ground layer inside thereof, component
pads on an upper surface thereof, and printed wiring
35 board pads on a lower surface thereof, the component pads being connected to terminals of a second component larger in size than the first component,

the printed wiring board pads being connected to pads on the printed wiring board, the component pads and the printed wiring board pads being electrically connected, the component pads including component ground pads connected to a plurality of ground terminals of the component and to the ground layer connected to a ground pad for the printed wiring board, the printed wiring board pads being more dispersed than the component pads.

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9. An auxiliary substrate for hierarchical mounting mounted next to a first component mounted on a printed board, the auxiliary substrate for hierarchical mounting comprising:

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a power supply layer inside thereof, component pads on an upper surface thereof, and printed wiring board pads on a lower surface thereof, the component pads being connected to terminals of a second component larger in size than the first component, the printed wiring board pads being connected to pads on the printed wiring board, the component pads and the printed wiring board pads being electrically connected, the component pads including component power supply pads connected to a plurality of power supply terminals of the component and to the power supply layer connected to a power supply pad for the printed wiring board, the power supply terminals being of equal potentials, the printed wiring board pads being more dispersed than the component pads.

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10. An auxiliary substrate for hierarchical mounting mounted next to a first component mounted on a printed board, the auxiliary substrate for hierarchical mounting comprising:

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a ground layer and a power supply layer inside thereof, component pads on an upper surface

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thereof, and printed wiring board pads on a lower surface thereof, the component pads being connected to terminals of a second component larger in size than the first component, the printed wiring board pads being connected to pads on the printed wiring board, the component pads and the printed wiring board pads being electrically connected, the component pads including component ground pads connected to a plurality of ground terminals of the component and to the ground layer connected to a ground pad for the printed wiring board, the component pads including component power supply pads connected to a plurality of power supply terminals of the component and to the power supply layer connected to a power supply pad for the printed wiring board, the power supply terminals being of equal potentials, the printed wiring board pads being more dispersed than the component pads.

11. The auxiliary substrate for hierarchical mounting as claimed in claim 7, characterized by having a frame-like shape, a U-shape, or a shape of two separated sticks.

12. An electronic apparatus having the printed wiring board unit claimed in claim 1 loaded inside thereof.